







AMC60804T SLASF79 - JANUARY 2023

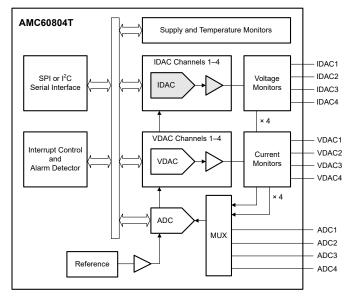
AMC60804T 4-Channel Optical Monitor and Controller With Current and Voltage Output DACs and Multichannel ADC

1 Features

- Four 12-bit current output DACs (IDACs)
 - 200-mA full-scale output range
 - Low supply headroom: 200 mV at 200 mA
- Four 12-bit voltage output DACs (VDACs)
 - Selectable full-scale output ranges: -5 V, -2.5 V, +2.5 V and +5 V
- High-current drive capability: ±50 mA
- Multichannel, 12-bit, 1-MSPS SAR ADC
 - Four external inputs: 2.5-V and 5-V ranges
 - Four IDAC voltage monitor channels
 - Four VDAC current monitor channels
 - Programmable sequencer
 - Programmable out-of-range alarms
- Internal 2.5-V reference
- Supply and temperature fault alarms
- SPI and I²C interfaces: 1.7-V to 3.6-V operation
 - SPI: 4-wire interface
 - I²C: Four target addresses
- Specified temperature range: -40°C to +125°C

2 Applications

- Optical module
- Intra-DC interconnect (metro)



Simplified Schematic

3 Description

The AMC60804T is a highly integrated, low-power analog monitor and controller for optical transceiver applications.

The AMC60804T includes four 12-bit current output digital-to-analog converters (IDACs) and four 12-bit voltage output DACs (VDACs) with programmable output ranges. The device also includes a 12-bit, 1-MSPS analog-to-digital converter (ADC) used for external and internal signal monitoring, supply and temperature alarm monitors, and a high-precision internal reference.

The AMC60804T VDACs support both positive and negative output-range operation and are capable or sourcing and sinking up to 50 mA, making them an excellent choice for biasing optical modulators. Additionally, the AMC60804T IDACs support a fullscale output range of 200 mA with very-low power dissipation. The IDACs eliminate the need for external components to bias laser diodes. In combination, the AMC60804T four VDACs and four IDACs enable accurate biasing of electro-absorption modulated

The AMC60804T also includes four input pins that are multiplexed to the ADC and incorporate a lowlatency window comparator. These features make this device an excellent choice for received signal strength indicator (RSSI) and loss-of-signal (LOS) detection. The ADC is also capable of measuring the voltage at the IDAC pins, as well as the current being sourced or sinked by the VDACs, thus enabling these outputs to be monitored.

The AMC60804T low power, high integration, very small size, and wide operating temperature range make this device an excellent choice as an all-in-one control circuit for optical modules.

Package Information

	U							
PART NUMBER	PACKAGE ⁽¹⁾	BODY SIZE (NOM)						
AMC60804T	YBH (DSBGA, 36)	2.56 mm × 2.56 mm						

For all available packages, see the package option addendum at the end of the data sheet.



4 Device and Documentation Support

4.1 Documentation Support

Note

TI is transitioning to use more inclusive terminology. Some language may be different than what you would expect to see for certain technology areas.

4.1.1 Related Documentation

For related documentation, see the following: AMC60304EVM user's guide

4.2 Trademarks

All trademarks are the property of their respective owners.

4.3 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

4.4 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Submit Document Feedback

Copyright © 2023 Texas Instruments Incorporated



www.ti.com 26-Jan-2023

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
AMC60804TYBHR	ACTIVE	DSBGA	YBH	36	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 125	AMC60804T	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

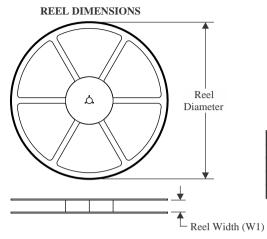
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

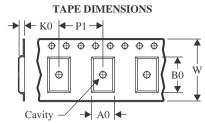
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 27-Jan-2023

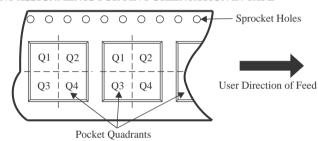
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

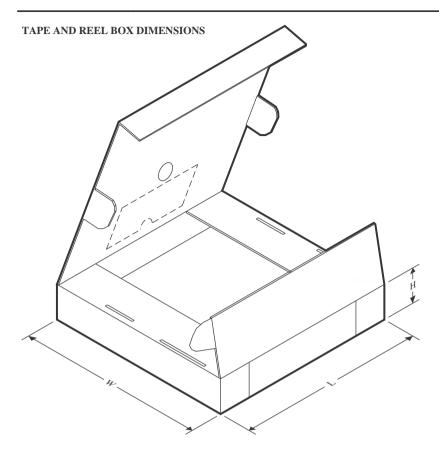


*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ĺ	AMC60804TYBHR	DSBGA	YBH	36	3000	180.0	8.4	2.71	2.71	0.6	4.0	8.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 27-Jan-2023



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
AMC60804TYBHR	DSBGA	YBH	36	3000	182.0	182.0	20.0	

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2023, Texas Instruments Incorporated